

2SC1741AM

Rev.F Apr.-2017



1VRW056 M M E QSQ Æ M y s ll 1 Silicon NPN 1 3NPN 25 Tw[S2stor in1 Tf411.057103 Tc0.0025 Tw[DA)230

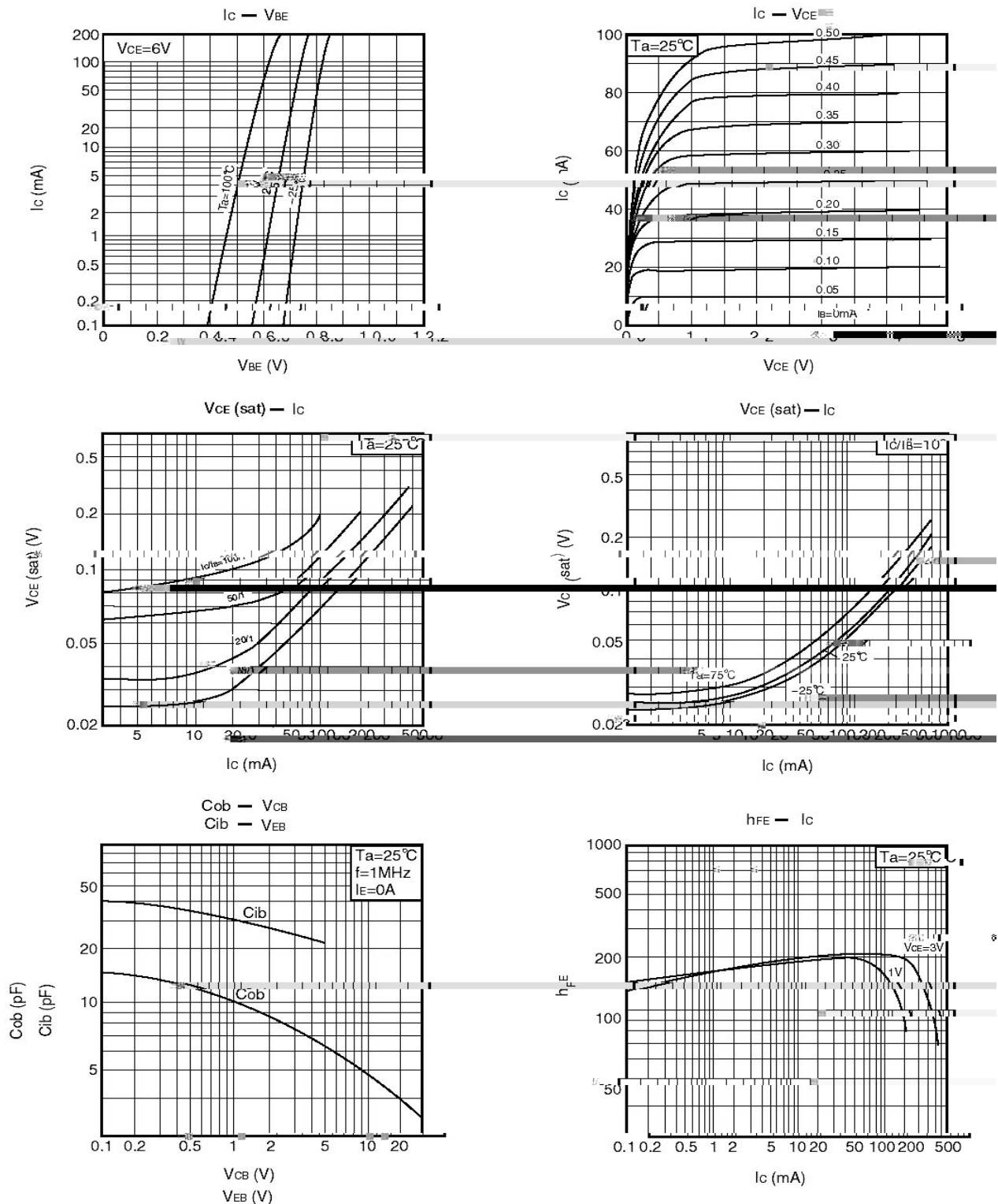
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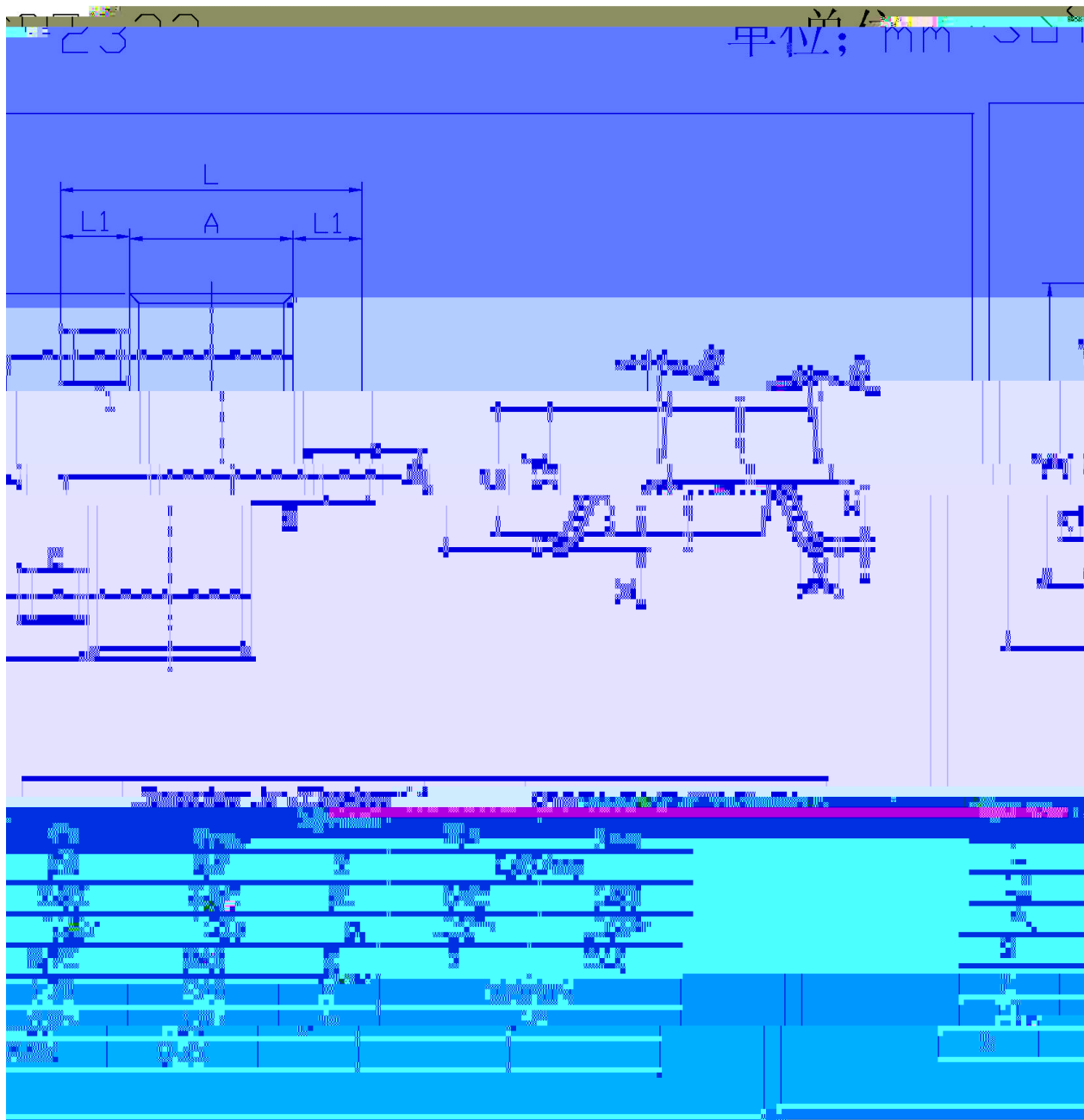
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	50	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current	I_C	0.5	A
Collector Power Dissipation	P_C	0.3	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55~150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector-Base Breakdown voltage	V_{CBO}	$I_C=100\text{ A}$ $I_E=0$	50			V
Collector-Emitter Breakdown voltage						V

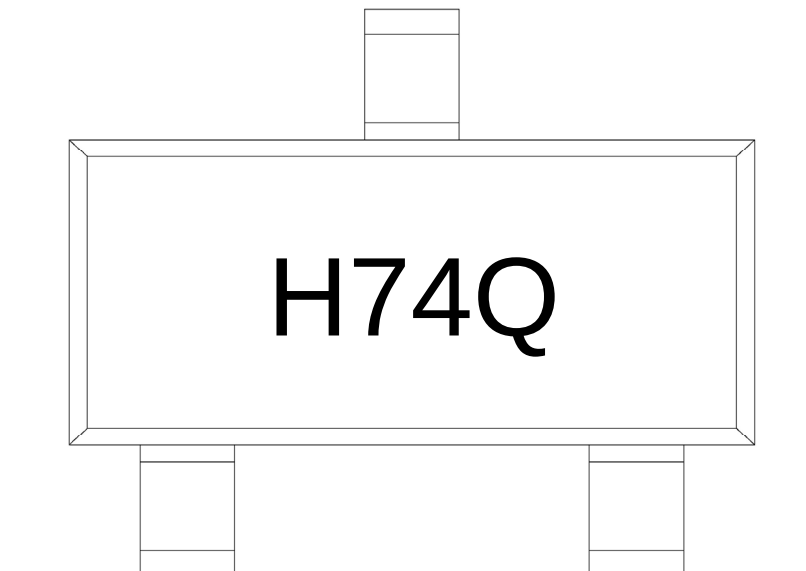
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



б " X

K X № 3¹ П

:7 X № 3^N П

T X № k_{1H} ⁶ К П

Note:

H: Company Code

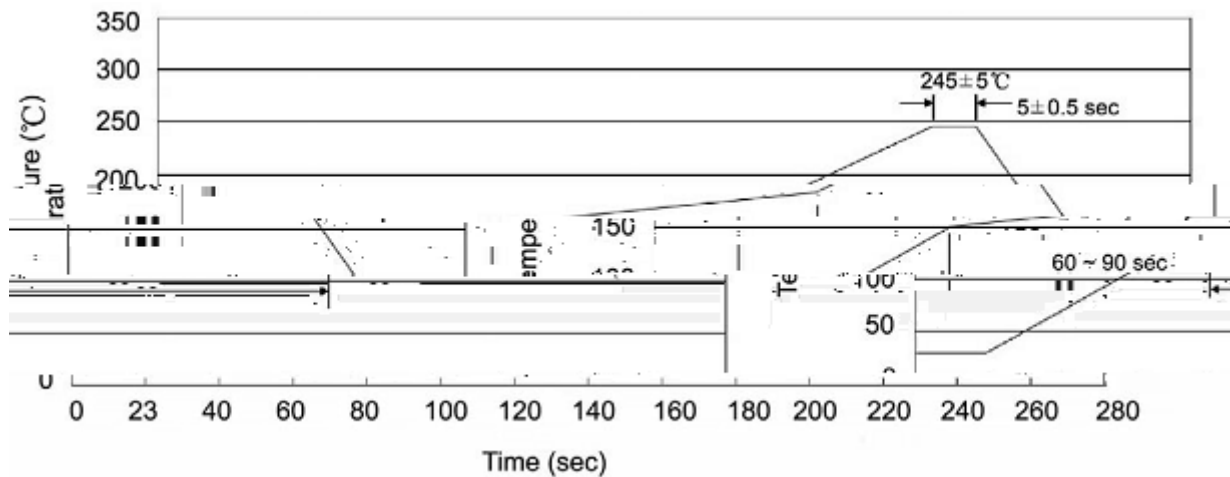
74: Product Type Code

Q: h_{FE} Classifications Symbol Code

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() / Temperature Profile for IR Reflow Soldering(Pb-Free)



1. 预加热: 25~150 °C, Time: 60~90sec;

2. 峰值温度: 245±5 °C, 持续时间: 5±0.5sec;

3. 冷却速度: 2~10 °C/sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.

2. Peak Temp.: 245±5 °C, Duration: 5±0.5sec.

3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

□ 预加热: 260±5 °C, Time: 10±1 sec.

Temp.: 260±5

Time: 10±1 sec

/ Packaging SPEC.

□ 预加热: REEL

Units

Dimension

(unit mm)